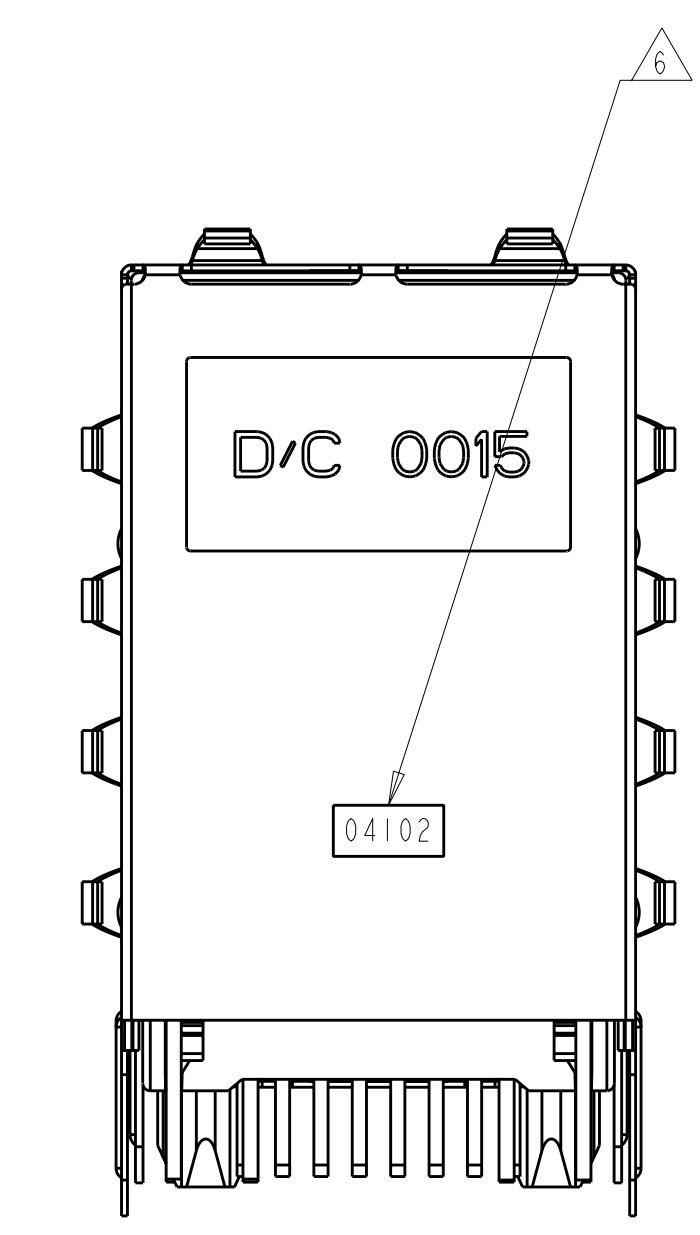
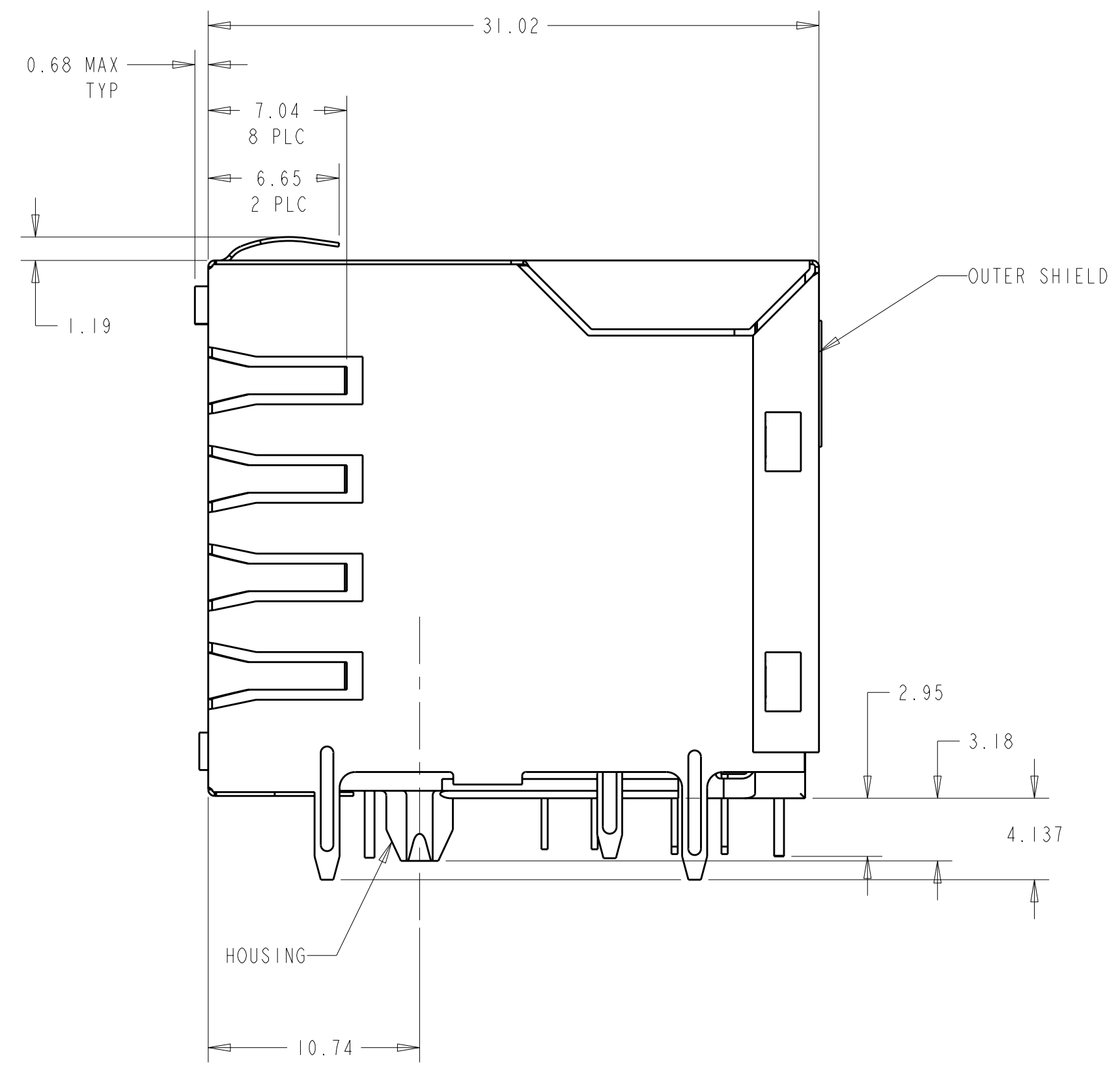
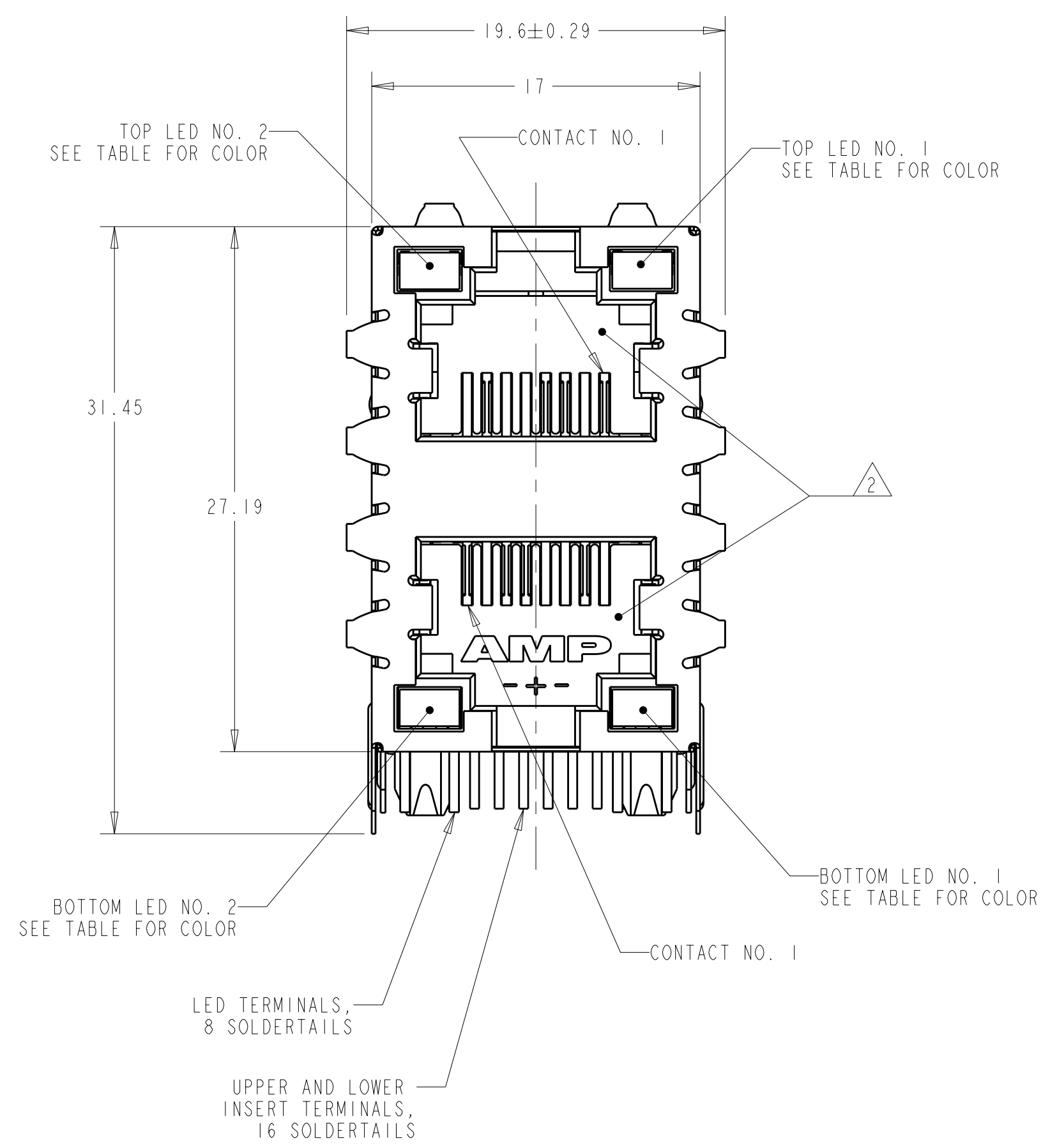
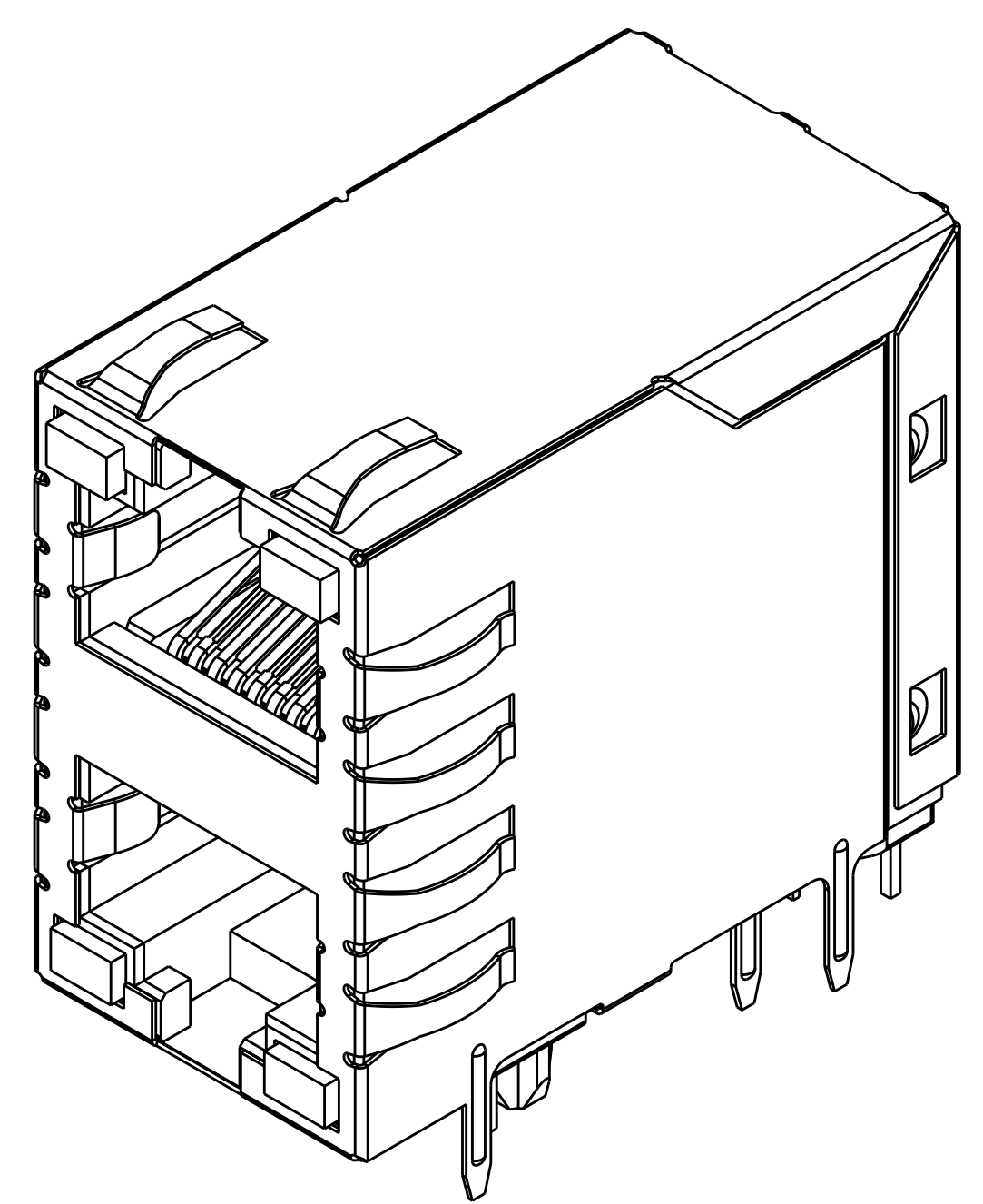
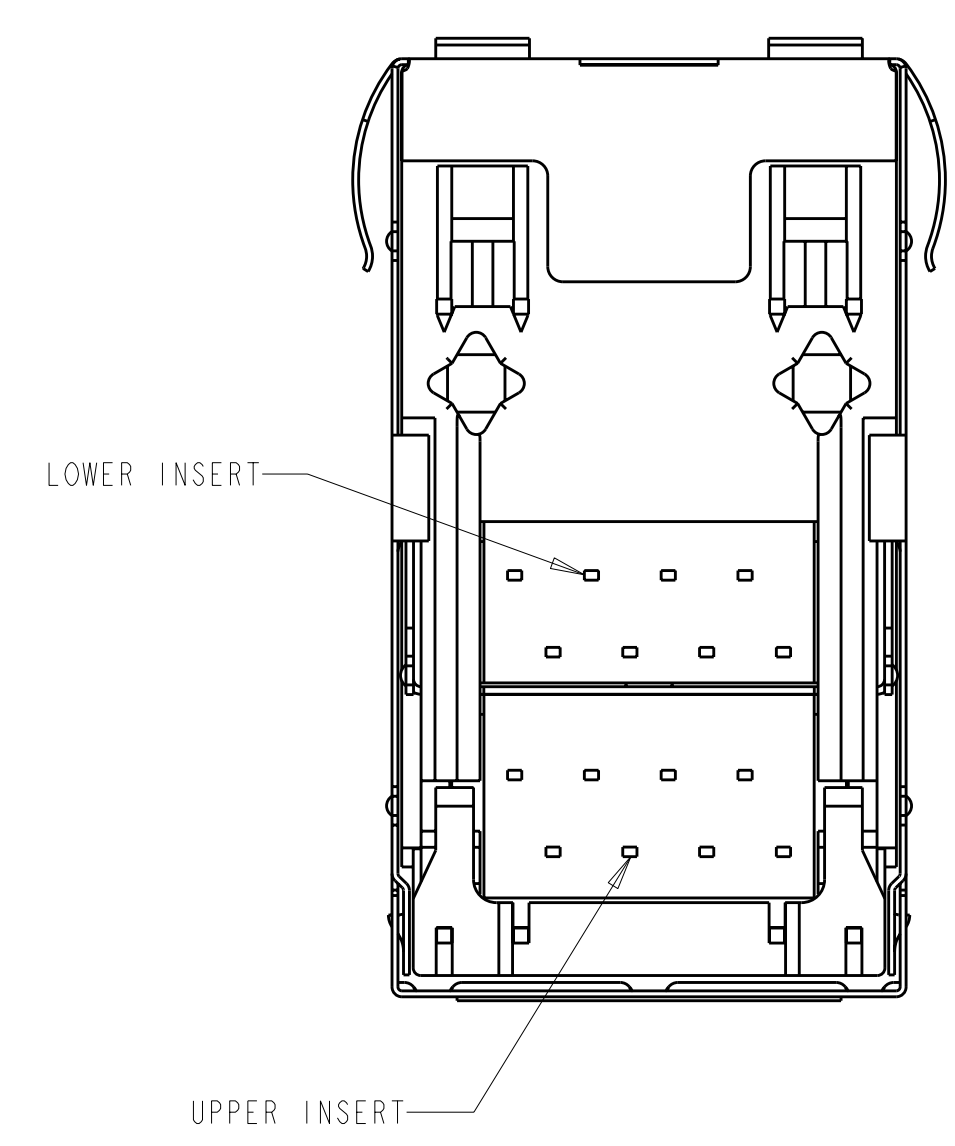


LOC		DIST		REVISIONS			
ES	00	P	LT#	DESCRIPTION	DATE	DNW	APVD
		A		RELEASED ECR-09-019321	31AUG2009	TY	SY
		B		REV PER ECR-09-016157	9MAR2010	DZ	SY

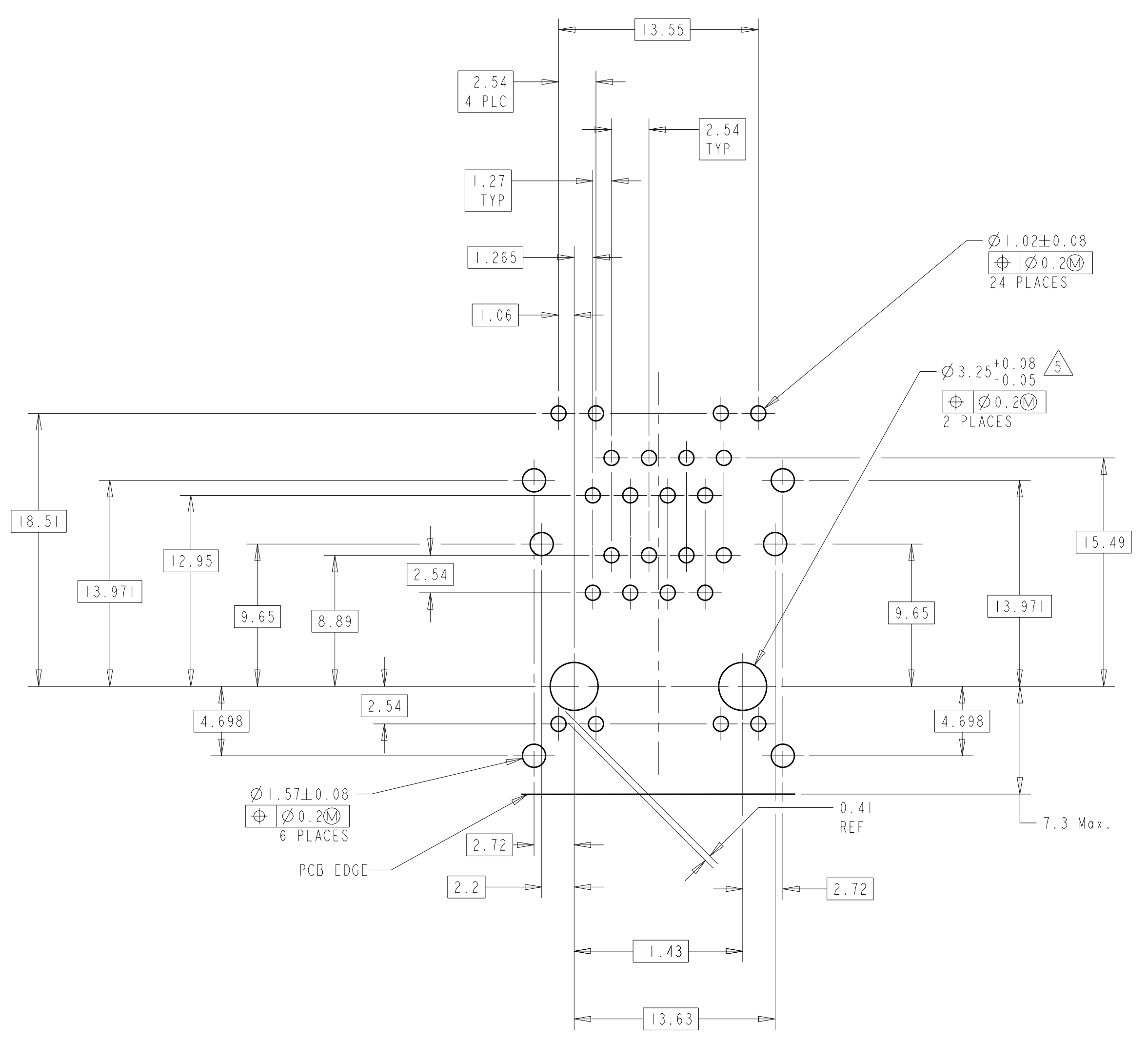


- 1 MATERIAL: HOUSING - PBT POLYESTER, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY-HTN
- TERMINALS - 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27um MINIMUM THICK HARD GOLD IN LOCALIZED MATING INTERFACE AND 3.81um MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27um MINIMUM THICK NICKEL UNDERPLATE.
- OUTER SHIELD - 0.196 THICK COPPER ALLOY PLATED WITH 1.27 um [.000050] MINIMUM NICKEL AND 2.03 um [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- INNER SHIELD -0.25 THICK COPPER ALLOY PLATED WITH 2.03 um MINIMUM BRIGHT TIN OVER 1.27 um MINIMUM NICKEL UNDERPLATE.
- LIGHT EMITTING DIODE (LED) - DIFUSED EPOXY LENS, 0.51 X 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 um THICK Sn/Cu OVER 2.03 um THICK Ag OVER 1.02 um THICK Cu OVER 3.56 um THICK Ni OVER 1.02 um Cu UNDERPLATE
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 SUGGESTED OPERATING CURRENT FOR THE LED IS 20mA.
- 4. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- 5 USE NO. 30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- 6 DATE CODE LOCATED ON REAR OF PART APPROX AS SHOWN: FIRST 2 DIGITS ARE LAST 2 DIGITS OF YEAR, SECOND 2 DIGITS ARE MANUFACTURING WORK WEEK, LAST DIGIT IS DAY OF WEEK, WITH SUNDAY=1.
- 7 MATERIAL: HOUSING - PBT POLYESTER, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY-HTN
- TERMINALS - 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27um MINIMUM THICK HARD GOLD IN LOCALIZED MATING INTERFACE AND 3.81um MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27um MINIMUM THICK NICKEL UNDERPLATE.
- OUTER SHIELD - 0.196 THICK COPPER ALLOY PLATED WITH 1.27 um [.000050] MINIMUM NICKEL AND 2.03 um [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- INNER SHIELD -0.25 THICK COPPER ALLOY PLATED WITH 2.03 um MINIMUM MATTE TIN OVER 1.27 um MINIMUM NICKEL UNDERPLATE..
- LIGHT EMITTING DIODE (LED) - DIFUSED EPOXY LENS, 0.51 X 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 um THICK Sn/Cu OVER 2.03 um THICK Ag OVER 1.02 THICK Cu OVER 3.56 um THICK Ni OVER 1.02 um Cu UNDERPLATE
- 8. OPERATING TEMPERATURE FROM -40 °C TO +80 °C

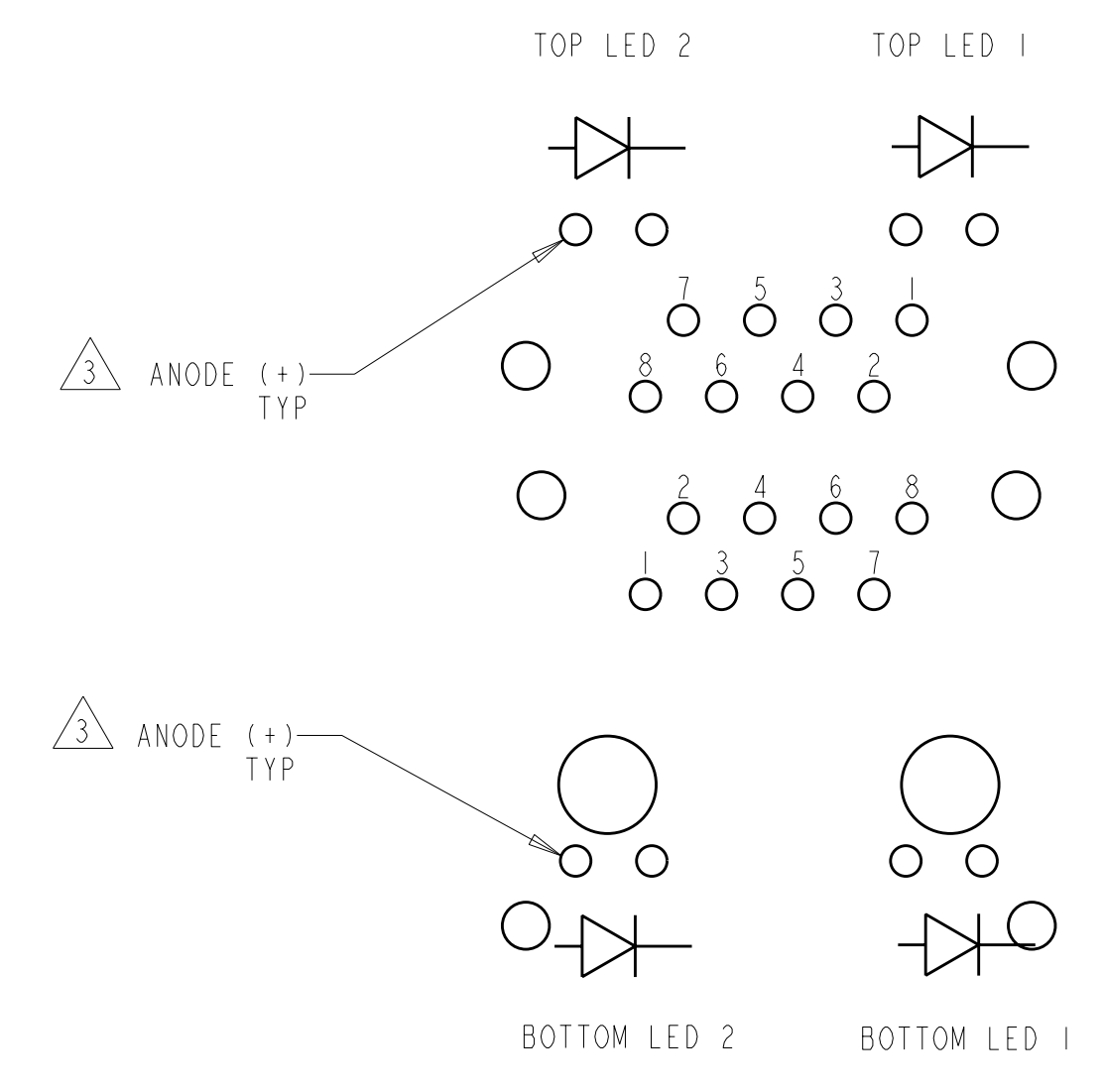


DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		DWN		APVD		NAME							
mm	0 PLC ±	1 PLC ±	2 PLC ±0.25	3 PLC ±0.25	4 PLC ±	ANGLES ±	FINISH	D_ZHU	22JUN2009	M_LI	22JUN2009	S_YAO	22JUN2009	TYCO Electronics	Tyco Electronics Corporation Shanghai, P.R. China, 200233
MATERIAL SEE NOTE 1,7		FINISH SEE NOTE 1,7		PRODUCT SPEC		APPLICATION SPEC		SIZE		CAGE CODE		DRAWING NO		RESTRICTED TO	
				108-1163-2		114-2154		A1		00779		C=1932391		CUSTOMER DRAWING	
				SCALE		1:1		SHEET		1		OF		2	
				REV		B									

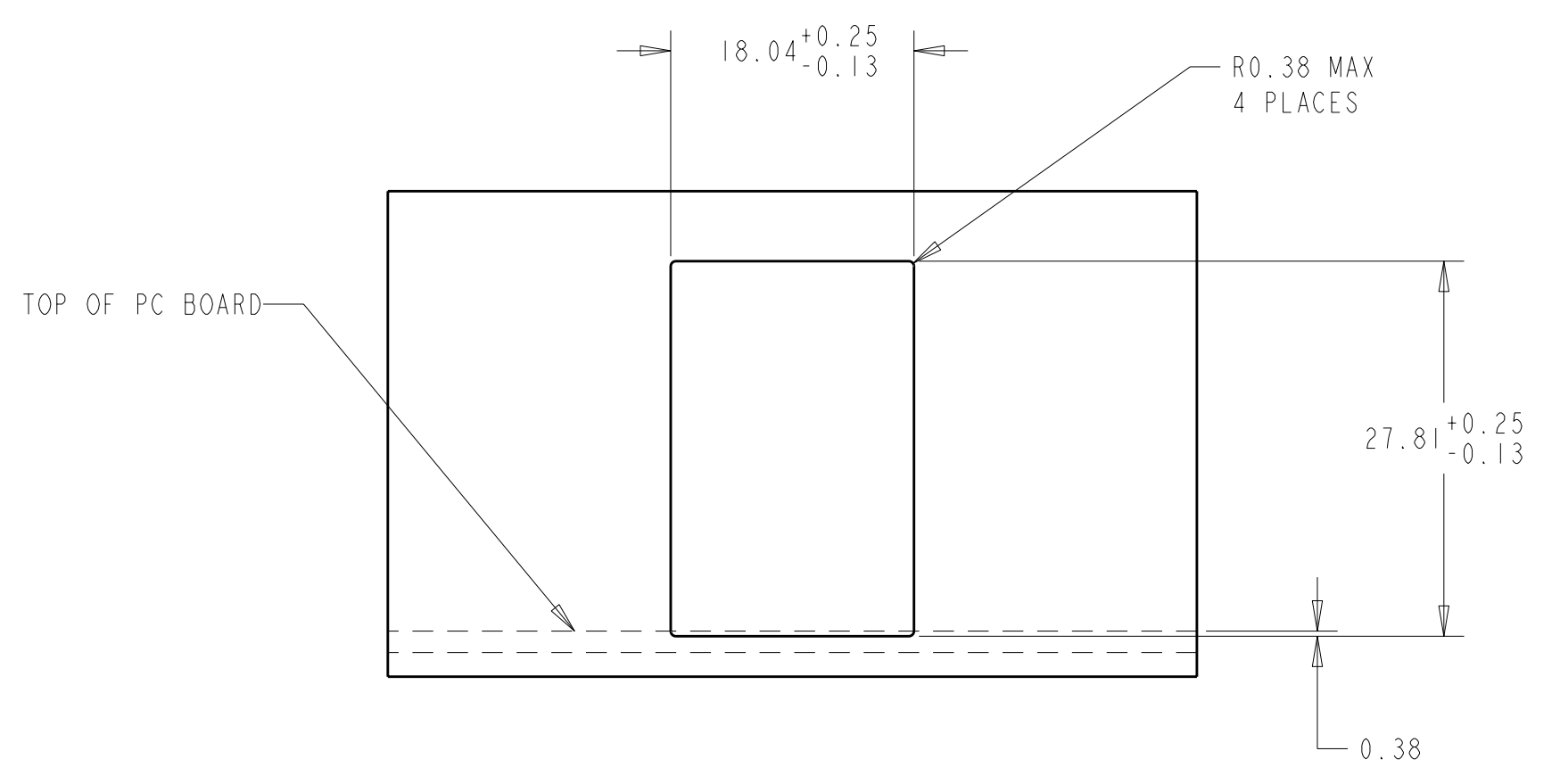
LOC	DIST	REVISIONS			
ES	00	REV	DATE	BY	APPD
		-	SEE SHEET 1	-	-



PC BOARD LAYOUT VIEWED FROM COMPONENT SIDE OF BOARD
 SCALE 4:1



SCALE 4:1



SUGGESTED PANEL CUTOUT DIMENSIONS
 SCALE 2:1

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DIMENSIONS: mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ± 1 PLC ±0.25 5 PLC ±0.25 4 PLC ± ANGLES ±	NAME: MODULAR JACK ASSEMBLY, STACKED, 2 X 1, 8 POSITION, SHIELDED, PANEL GROUND, LED, CATEGORY 5 PRODUCT SPEC: 108-1163-2 APPLICATION SPEC: 114-2154	SIZE: A1 CAGE CODE: 00779 DRAWING NO: C=1932391
MATERIAL: SEE NOTE 1	FINISH: SEE NOTE 1	WEIGHT: -	RESTRICTED TO: -
CUSTOMER DRAWING		SCALE: 1:1	SHEET 2 OF 2 REV A1